

# BAT74

## Schottky barrier double diode

Rev. 03 — 19 April 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Schottky barrier double diode with an integrated guard ring for stress protection. Two electrically isolated Schottky barrier diodes, encapsulated in a small SOT143B Surface-Mounted Device (SMD) plastic package.

### 1.2 Features and benefits

- Low forward voltage
- Guard-ring protected
- Small SMD plastic package

### 1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$I_F$	forward current		-	-	200	mA
$V_R$	reverse voltage		-	-	30	V
$V_F$	forward voltage	$I_F = 100 \text{ mA}$	-	-	800	mV

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode (diode 1)		
2	cathode (diode 2)		
3	anode (diode 2)		
4	anode (diode 1)		

### 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT74	-	plastic surface-mounted package; 4 leads	SOT143B

### 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
BAT74	*L4

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

### 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per diode</b>					
$V_R$	reverse voltage		-	30	V
$I_F$	forward current		-	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p < 10$ ms	-	600	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	-	230	mW
$T_j$	junction temperature		-	125	°C
$T_{amb}$	ambient temperature		-65	+125	°C
$T_{stg}$	storage temperature		-65	+150	°C
<b>Double diode operation</b>					
$V_R$	reverse voltage		-	30	V
		[1]	-	60	V
$I_F$	forward current		[2]	110	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	200	mA

[1] Series connection.

[2] If both diodes are in forward operation at the same moment, total device current is max. 110 mA. If one diode is in reverse operation and the other is in forward operation at the same moment, total device current is max. 200 mA.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W

[1] Refer to SOT143B standard mounting conditions.

## 7. Characteristics

**Table 7. Characteristics**

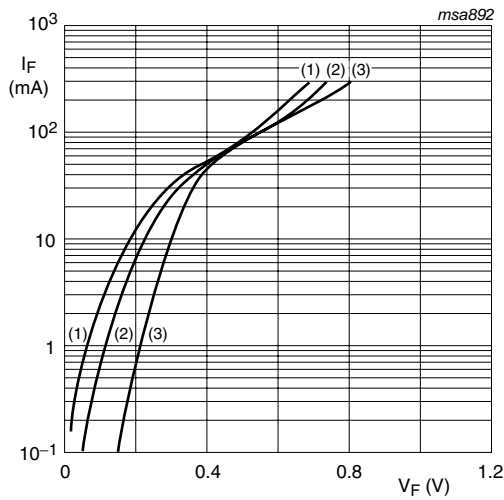
$T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$V_F$	forward voltage	$I_F = 0.1\text{ mA}$	-	-	240	mV
		$I_F = 1\text{ mA}$	[1]	-	320	mV
		$I_F = 10\text{ mA}$	-	-	400	mV
		$I_F = 30\text{ mA}$	-	-	500	mV
		$I_F = 100\text{ mA}$	-	-	800	mV
$I_R$	reverse current	$V_R = 25\text{ V}$	[2]	-	2	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	-	10	pF
$t_{rr}$	reverse recovery time		[3]	-	5	ns

[1] Temperature coefficient of forward voltage  $-0.6\text{ %/K}$ .

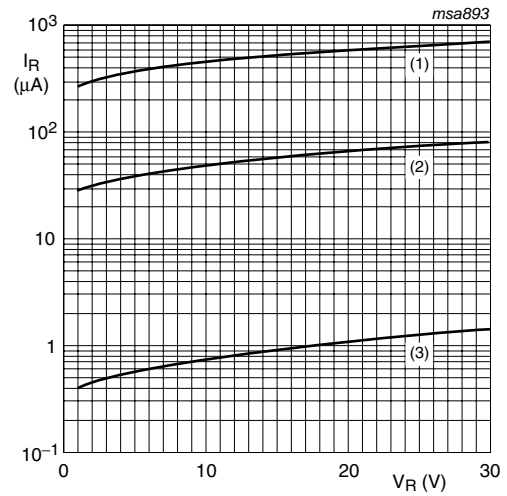
[2] Pulse test:  $t_p = 300\text{ }\mu\text{s}$ ;  $\delta = 0.02$ .

[3] When switched from  $I_F = 10\text{ mA}$  to  $I_R = 10\text{ mA}$ ;  $R_L = 100\text{ }\Omega$ ; measured at  $I_R = 1\text{ mA}$ .



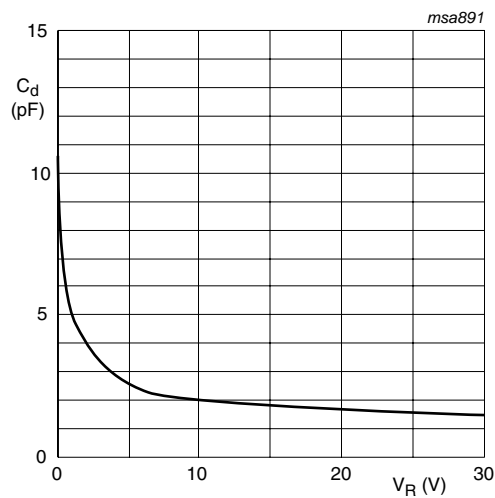
- (1)  $T_{amb} = 125\text{ °C}$
- (2)  $T_{amb} = 85\text{ °C}$
- (3)  $T_{amb} = 25\text{ °C}$

**Fig 1. Forward current as a function of forward voltage; typical values**



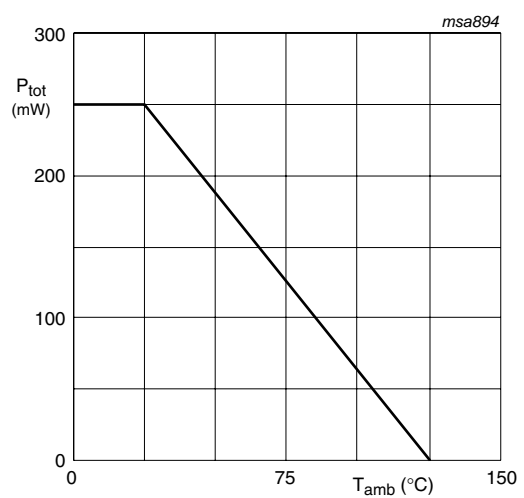
- (1)  $T_{amb} = 125\text{ °C}$
- (2)  $T_{amb} = 85\text{ °C}$
- (3)  $T_{amb} = 25\text{ °C}$

**Fig 2. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

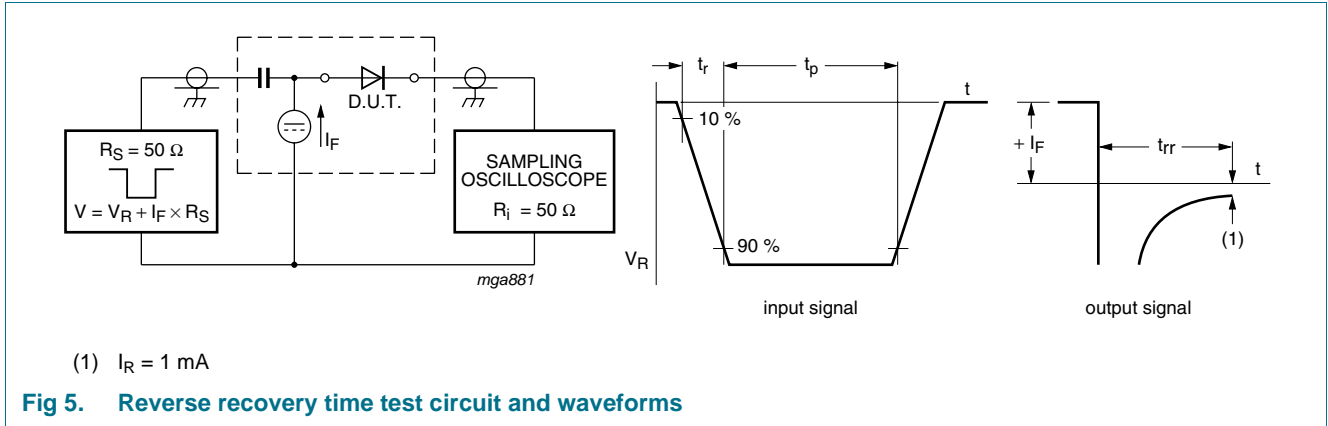
**Fig 3. Diode capacitance as a function of reverse voltage; typical values**



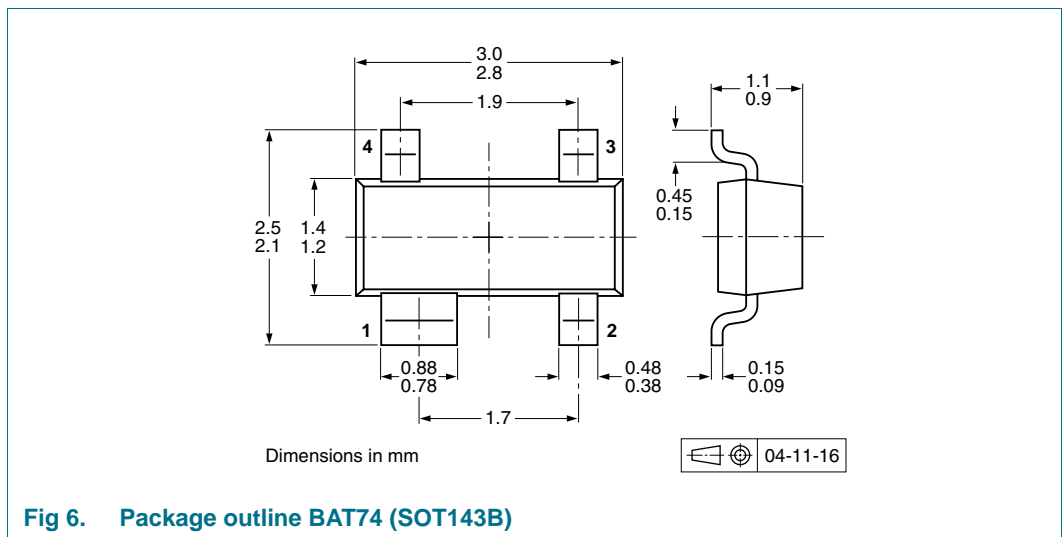
Standard footprint

**Fig 4. Power derating curve**

**8. Test information**



**9. Package outline**



**10. Packing information**

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
BAT74	SOT143B	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

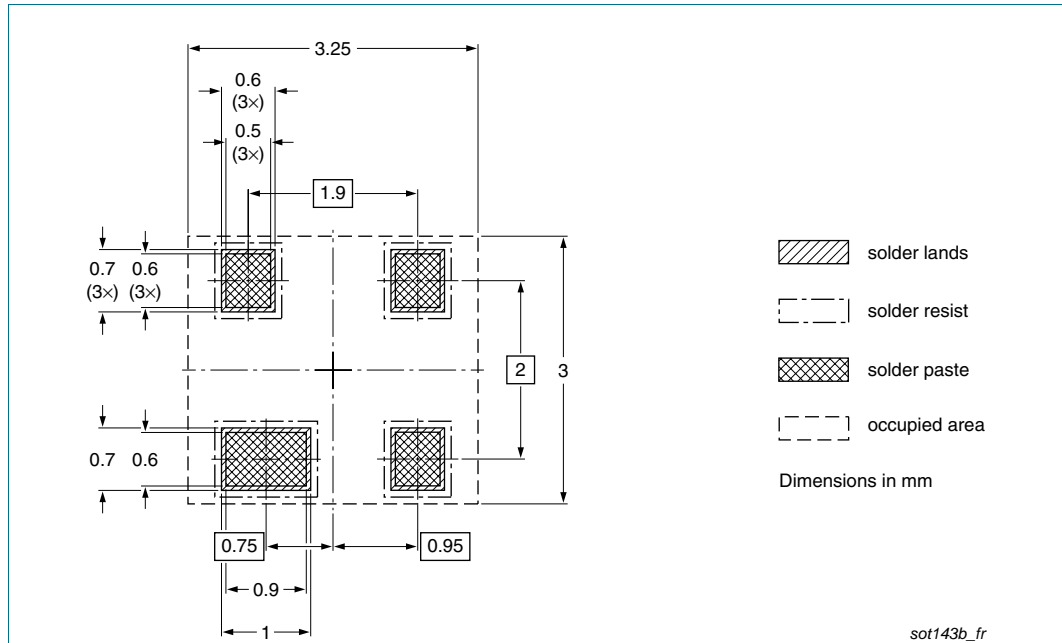


Fig 7. Reflow soldering footprint BAT74 (SOT143B)

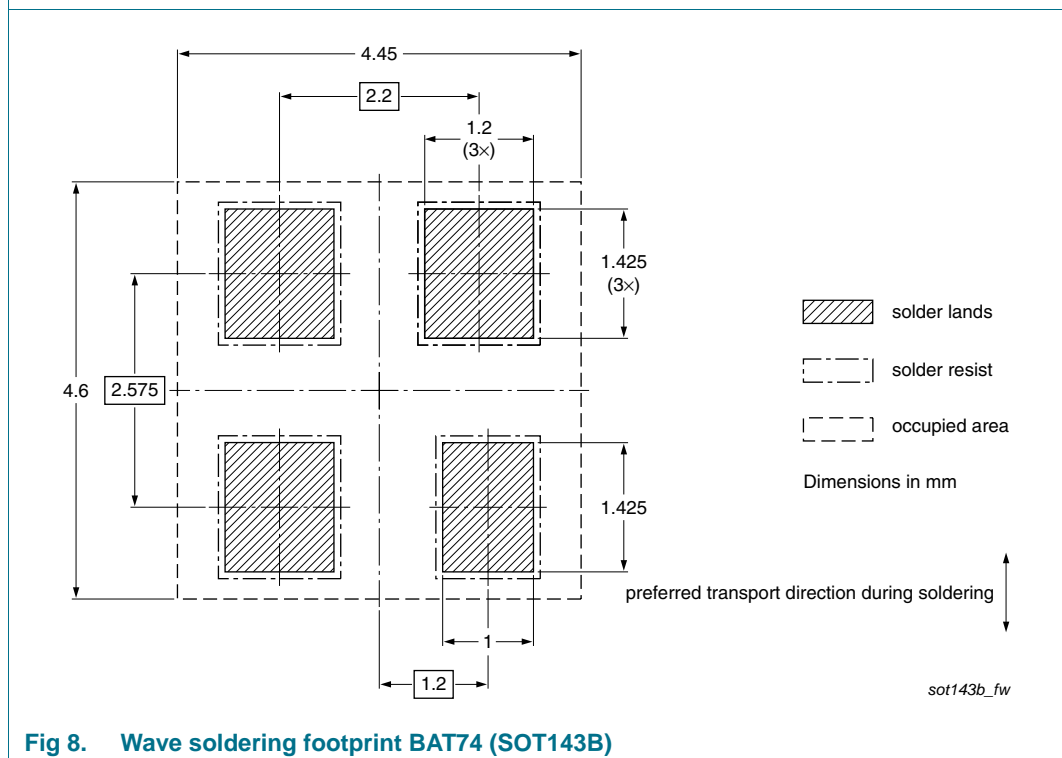


Fig 8. Wave soldering footprint BAT74 (SOT143B)

## 12. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAT74_3	20100419	Product data sheet	-	BAT74_2
Modifications:	<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Section 1.1 “General description”</a>: amended</li> <li>• <a href="#">Table 1 “Quick reference data”</a>: added</li> <li>• <a href="#">Section 4 “Marking”</a>: updated</li> <li>• <a href="#">Section 8 “Test information”</a>: added</li> <li>• <a href="#">Figure 5</a>: enhanced</li> <li>• <a href="#">Figure 6</a>: superseded by minimized package outline drawing</li> <li>• <a href="#">Section 10 “Packing information”</a>: added</li> <li>• <a href="#">Section 11 “Soldering”</a>: added</li> <li>• <a href="#">Section 13 “Legal information”</a>: updated</li> </ul>			
BAT74_2	20010905	Product specification	-	BAT74_1
BAT74_1	19960319	Product specification	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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